/ Descriptions

TO-252 N MOS
N-CHANNEL MOSFET in a TO-252 Plastic Package.

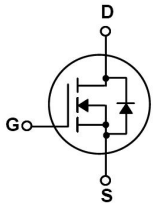
/ Features

, ,
Low gate charge, low crss, fast switching,HF Product.

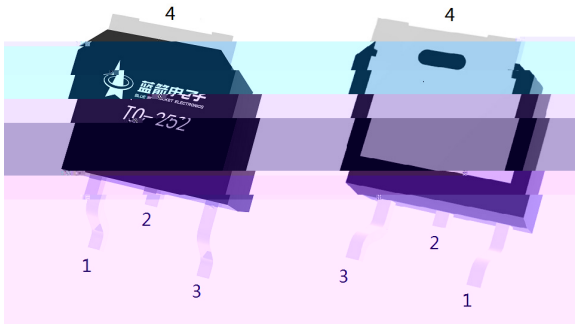
/ Applications

DC/DC
These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

/ Equivalent Circuit



/ Pinning



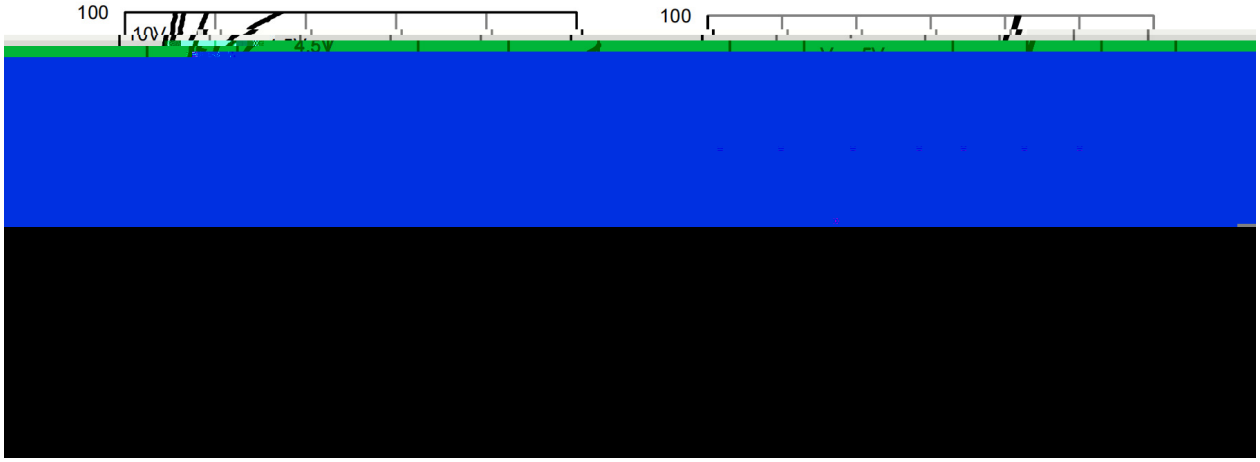
PIN1 G PIN 2 D PIN 3 S PIN 4 D

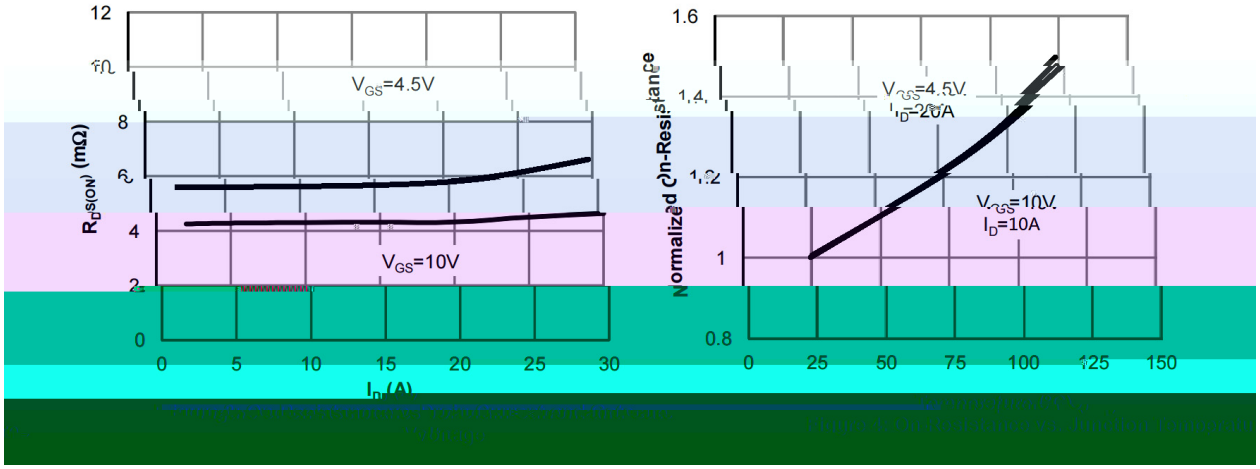
/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Drain Current	I_D(Tc=25)	85	A
Peak Drain Current	I_{DM}	280	A
Gate-Source Voltage	V_{GSS}	20	V
Avalanche Current	I_{AS}	26	A
Single Pulsed Avalanche Energy	E_{AS}	354	mJ
Total Power Dissipation	P_D(Tc=25)	100	W
Junction and Storage Temperature Range	T_J,T_{STG}	-55 to 150	
Thermal resistance, junction - ambient t ≤ 10s	$R_{\theta JA}$	20	

/ Electrical Characteristic Curve





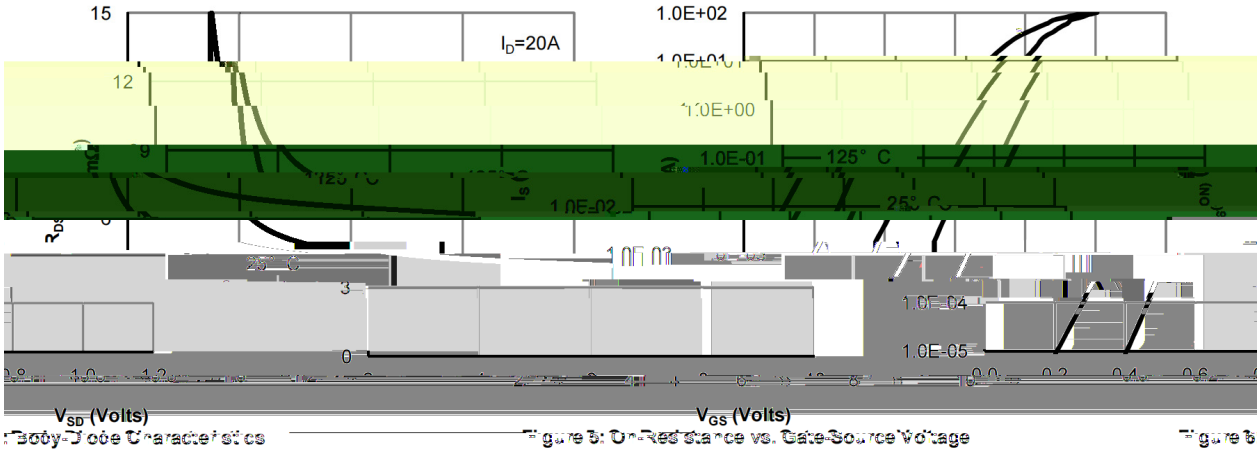
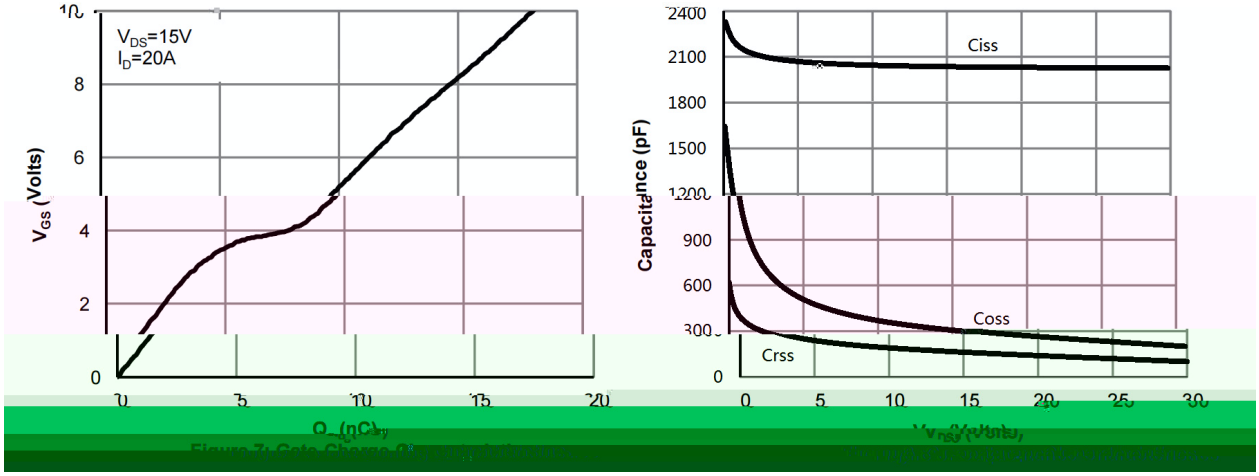
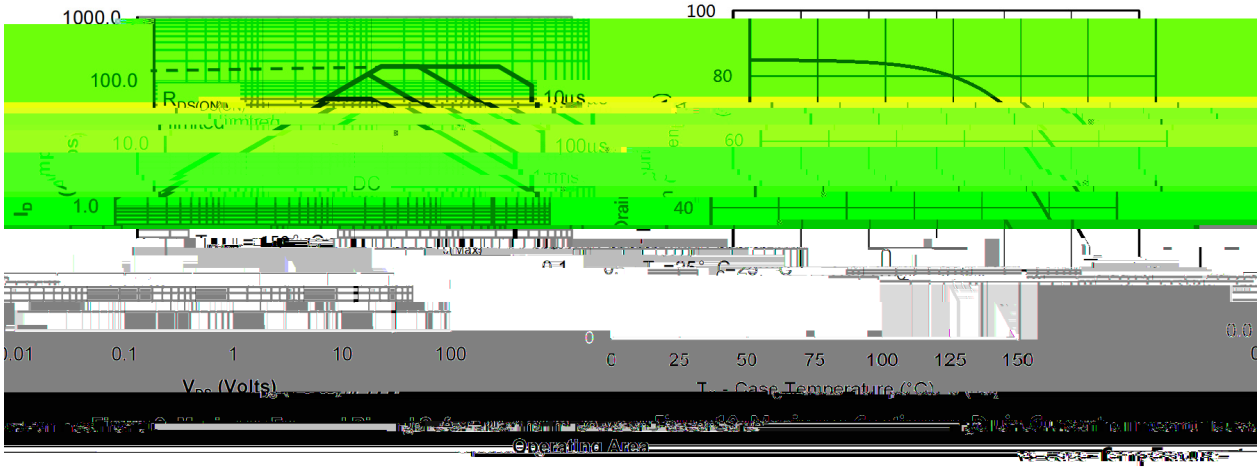
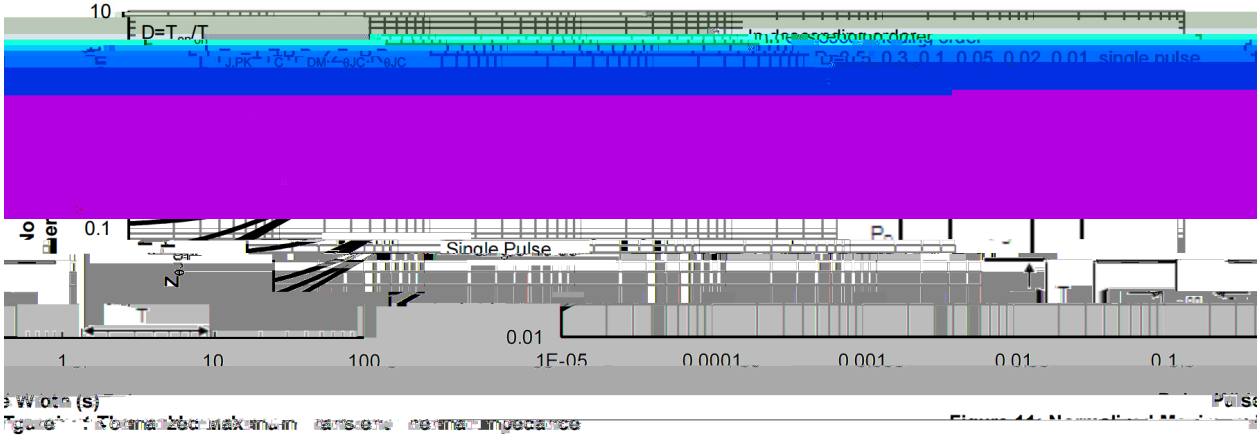


Figure 5: Body-Diode Characteristics — Figure 6: On-Resistance vs. Gate-Source Voltage — Figure 6

/ Electrical Characteristic Curve

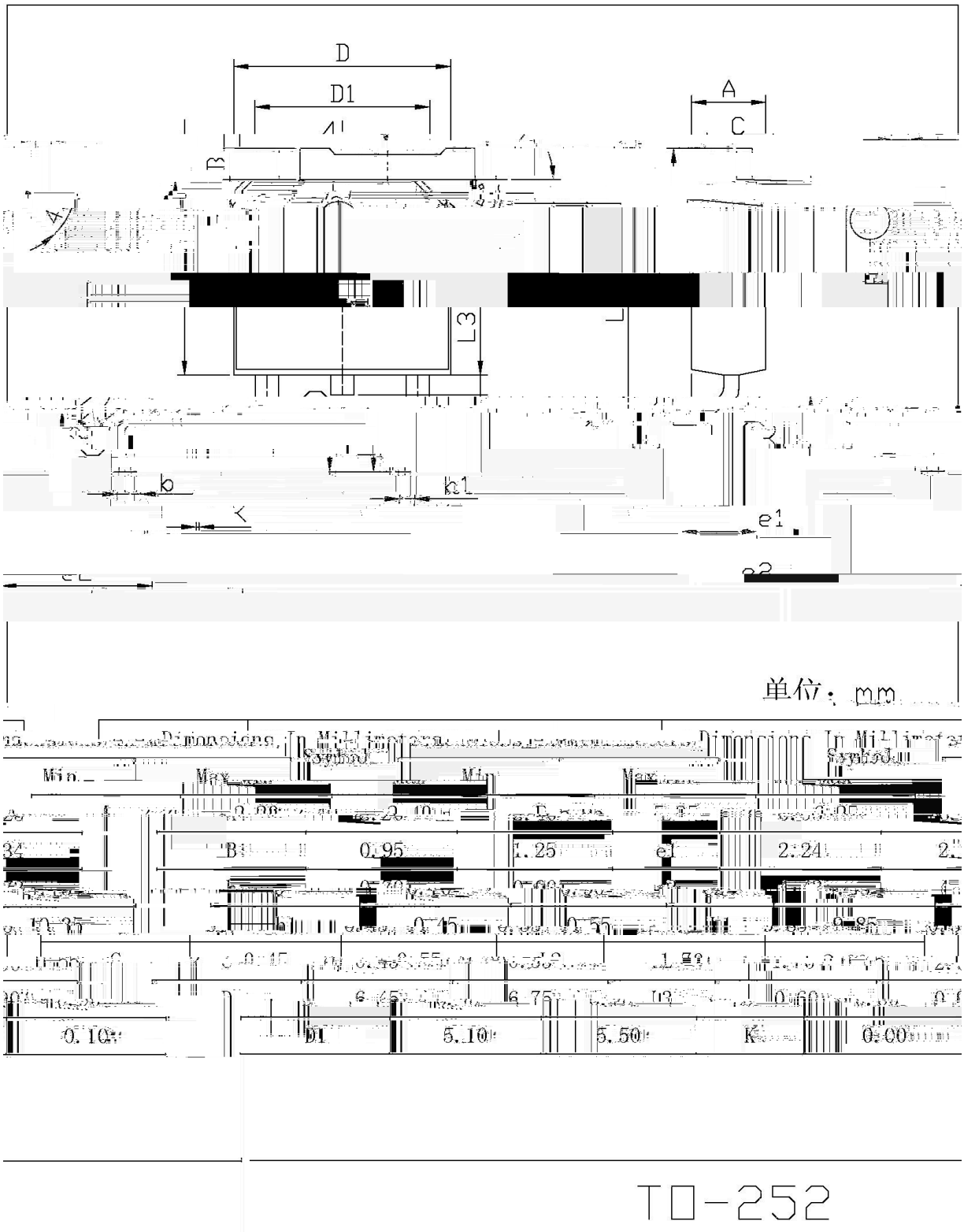




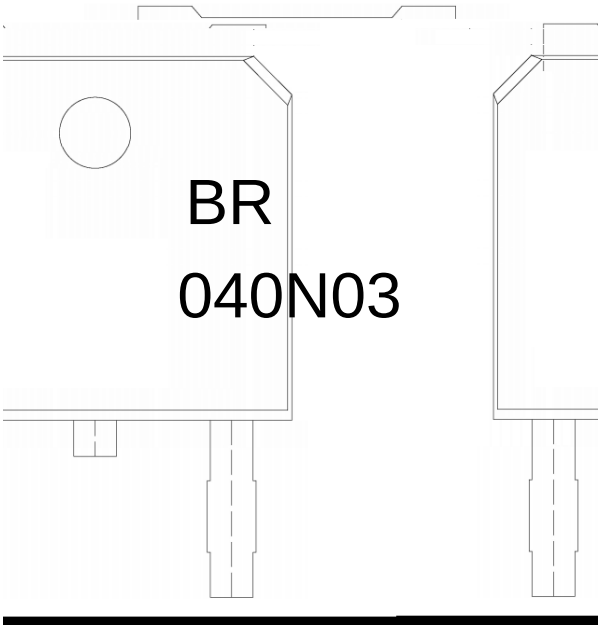


/ Package Dimensions

TO-252#



/ Marking Instructions



BR

040N03

****

Note:

BR:	Company Code
040N03:	Product Type
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1 150 180 60 90sec;

2 245±5 5±0.5sec;

3 2 10 /sec.

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm³)